

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
20 January 2005 (20.01.2005)

PCT

(10) International Publication Number
WO 2005/006437 A1

(51) International Patent Classification⁷: **H01L 23/58**

(21) International Application Number:
PCT/IB2004/051117

(22) International Filing Date: 5 July 2004 (05.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
03102105.8 11 July 2003 (11.07.2003) EP

(71) Applicant (for DE only): **PHILIPS INTELLECTUAL
PROPERTY & STANDARDS GMBH** [DE/DE]; Stein-
damm 94, 20099 Hamburg (DE).

(71) Applicant (for AE, AG, AL, AM, AT, AU, AZ, BA, BB, BE,
BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CY, CZ,
DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM,
HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK,
LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ,
NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD,
SE, SG, SK, SL, SY, SZ, TJ, TM, TN, TR, TT, TZ, UA, UG,

UZ, VC, VN, YU, ZA, ZM, ZW only): **KONINKLIJKE
PHILIPS ELECTRONICS N. V.** [NL/NL]; Groenewoud-
seweg 1, NL-5621 BA Eindhoven (NL).

(72) Inventor; and

(75) Inventor/Applicant (for US only): **BRETSCHNEIDER,
Ernst** [DE/DE]; c/o Philips Intellectual Property &, Stan-
dards GmbH Weisshausstr. 2, 52066 Aachen (DE).

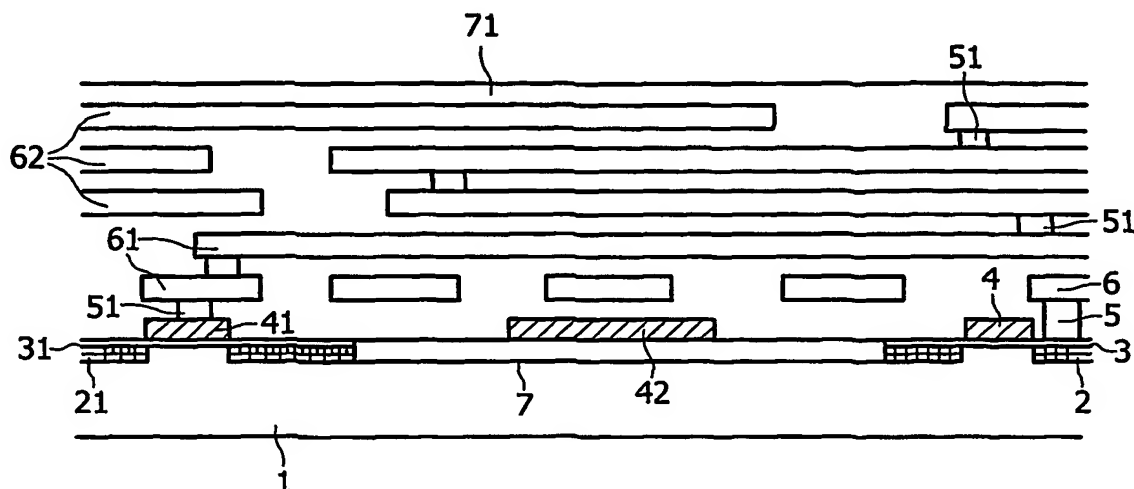
(74) Agent: **VOLMER, Georg**; Philips Intellectual Property
&, Standards GmbH Weisshausstr. 2, 52066 Aachen (DE).

(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN,
CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI,
GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG,
PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM,
TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM,
ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, GH,

[Continued on next page]

(54) Title: **SECURITY-SENSITIVE SEMICONDUCTOR PRODUCT, PARTICULARLY A SMART-CARD CHIP**



(57) Abstract: To provide a security-sensitive semiconductor product, particularly a smartcard chip, in which are produced not only electrically active structures (2, 3, 4, 5, 6) envisaged by the chip design in the form of circuit functions in and on a wafer (1), which may for example be composed of silicon, but also additional, electrically conductive parts (42, 61, 62) (tiles) of the filling structure, which are insulated from one another, are generated by means of a design program in the remaining residual areas, which greatly impedes, to the reverse engineer the analysis of the security-sensitive circuit structure situated beneath them. The contacts between the parts which are generated, which contacts are for interlinking the latter with the chance signal paths described, may be set "by hand" or by a combination of the design programs in question and a corresponding routing program. The filling conductive parts can also be connected to circuit components, such as transistors, diodes, resistors or capacitors, in order to provide additional circuit functions (e.g. analyzer circuits).

WO 2005/006437 A1

Published:

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